

DIELECTRIC RESIN COMPOSITION AND MULTILAYER CIRCUIT BOARD
COMPRISING DIELECTRIC LAYERS FORMED THEREFROM

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ABSTRACT OF THE DISCLOSURE

10 A dielectric resin composition comprising at least
one type of epoxy resin and at least one type of cyanate
ester which would react with said epoxy resin, together
with a metal ion catalyst system, the ratio of the epoxy
functional groups of said epoxy resin to the cyanate
15 groups of said cyanate ester being in the range of from
1:0.8 to 1:1.4. Alternatively, a dielectric resin
composition according to the invention may comprise a
polyimide resin with side chain epoxy groups, a cyanate
ester with two or more cyanate groups in the molecule,
and a metal ion catalyst system. A multilayer circuit
20 board having a multilayer structure comprising a core
substrate and a required number of dielectric layers and
wiring layers stacked alternately, wherein at least one
of the dielectric layers is formed from a dielectric
resin composition of the invention, is also disclosed.

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